



Device Material Content

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Package: 100 PQFP
Total Device Weight 1.600 Grams

Package Code:

YN

Products:

M4A

Assembly: ATP, Unisem

Size (mm): 14 x 20 x 2.7

Lead pitch (mm): 0.5

MSL: 3

Reflow max (°C): 245

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	1.11%	0.0178			Silicon chip	7440-21-3	100.00%	Die size: 3.38 x 3.54 x 0.64 mm
Mold Compound	84.37%	1.3499	5.91%	0.0945	Epoxy Resin	-	7.00%	Mold Compound: Sumitomo G700 series
			4.22%	0.0675	Phenol Resin	-	5.00%	
			0.42%	0.0067	Carbon Black	1333-86-4	0.50%	
			73.82%	1.1812	Silica Fused	60676-86-0	87.50%	
D/A Epoxy	0.08%	0.0013	0.06%	0.00102	Silver	7440-22-4	80.00%	Die attach: Ablebond 3230 or Sumitomo CRM1076NS
			0.02%	0.00026	Esters & resins	-	20.00%	
Wire	0.18%	0.0029	0.18%	0.0029	Gold (Au)	7440-57-5	100.00%	1.0 mil wire diameter; 1 wire for each package lead
Plating	1.38%	0.0221	1.38%	0.0221	Tin (Sn)	7440-31-5	100.00%	Plating is 100% Matte Sn; thickness is >10.2µm
Leadframe	12.88%	0.2061	12.45%	0.1993	Copper (Cu)	7440-50-8	96.70%	C7025
			0.39%	0.0062	Nickel (Ni)	7440-02-0	3.01%	
			0.02%	0.0004	Silicon (Si)	7440-21-3	0.17%	
			0.00%	0.0001	Magnesium (Mg)	7439-95-4	0.03%	
			0.01%	0.0002	Silver (Ag)	7440-22-4	0.09%	

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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